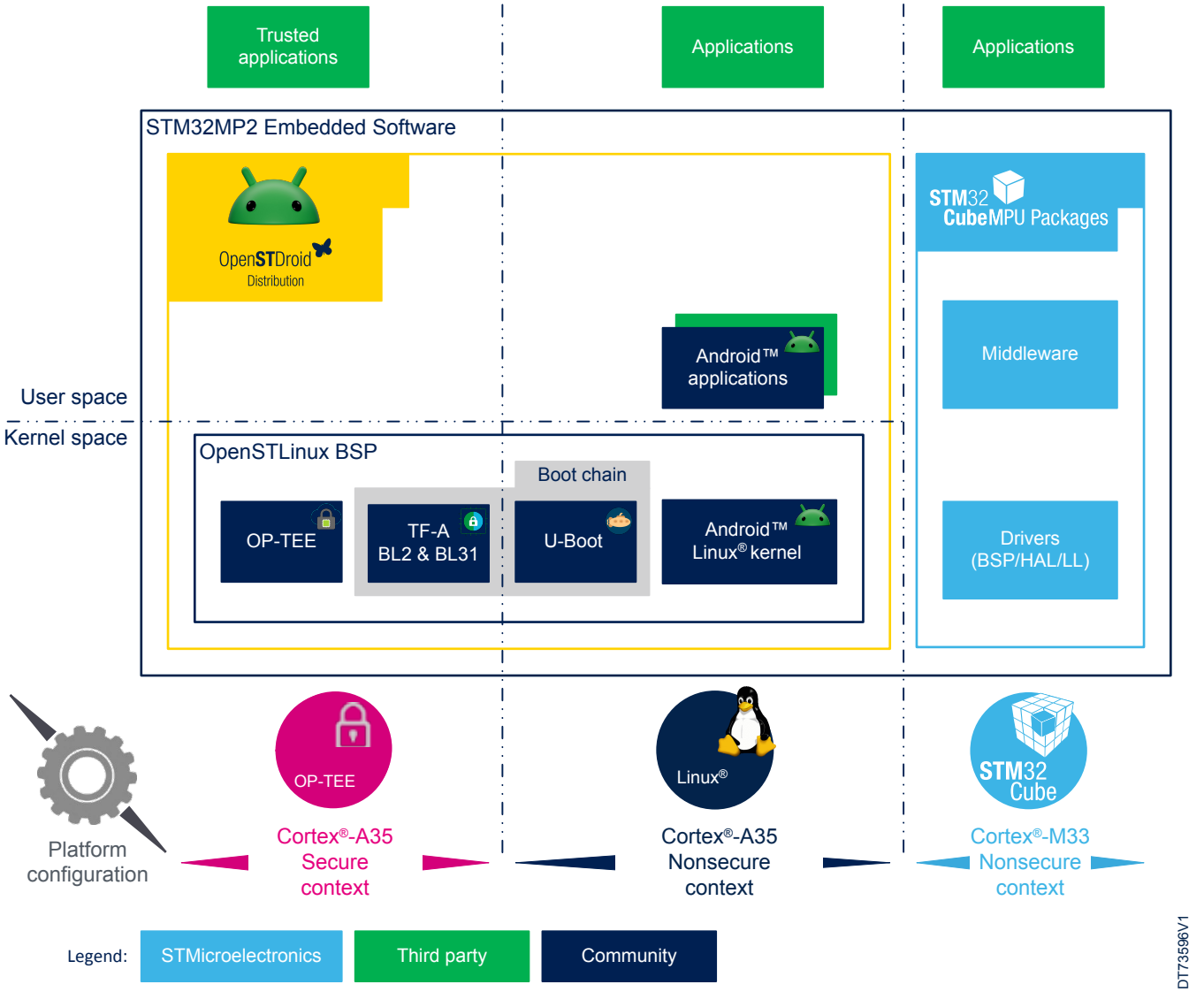
STM32MP2 OpenSTDroid Distribution Package



Product status link
STM32MP2DroidDis

Features

- STM32MP2 OpenSTDroid Distribution Package for Android™, composed of:
  - An Android™ build framework: the distribution builder
  - The OpenSTDroid Distribution for the development on the Arm® Cortex®-A processor
    - BSP prebuilt binaries (Linux® kernel, U-Boot, TF-A, OP-TEE)
    - Scripts to load source code and rebuild the BSP binaries
    - Application frameworks pieces in source code, including hardware abstraction code
  - The STM32CubeMP2 MPU Package for the development on the Arm® Cortex®-M processor
    - All pieces of software in source code: BSP, HAL, middleware, and applications
  - A toolset for users to:
    - Tune the system for their needs
    - Handle the built image, for example with STM32CubeProgrammer (STM32CubeProg) to install it on the board

Description

The STM32MP2DroidDis OpenSTDroid Distribution Package is the Android™ distribution based on the Android™ build framework.

In STM32MP2DroidDis, the OpenSTDroid Distribution is dedicated to the development on the Arm® Cortex®-A processor. It includes the Android™ application frameworks and the OpenSTLinux BSP (Linux® kernel, U-Boot, TF-A, and OP-TEE).

In STM32MP2DroidDis, the STM32CubeMP2 MPU Package targets the development on the Arm® Cortex®-M processor. It includes all pieces of software in source code: BSP, HAL, middleware, and applications.

STM32MP2DroidDis also contains a toolset to tune the system for the user's needs and to handle the built image. Use, for instance, STM32CubeProgrammer (STM32CubeProg) to install the built image on the board.

1 General information

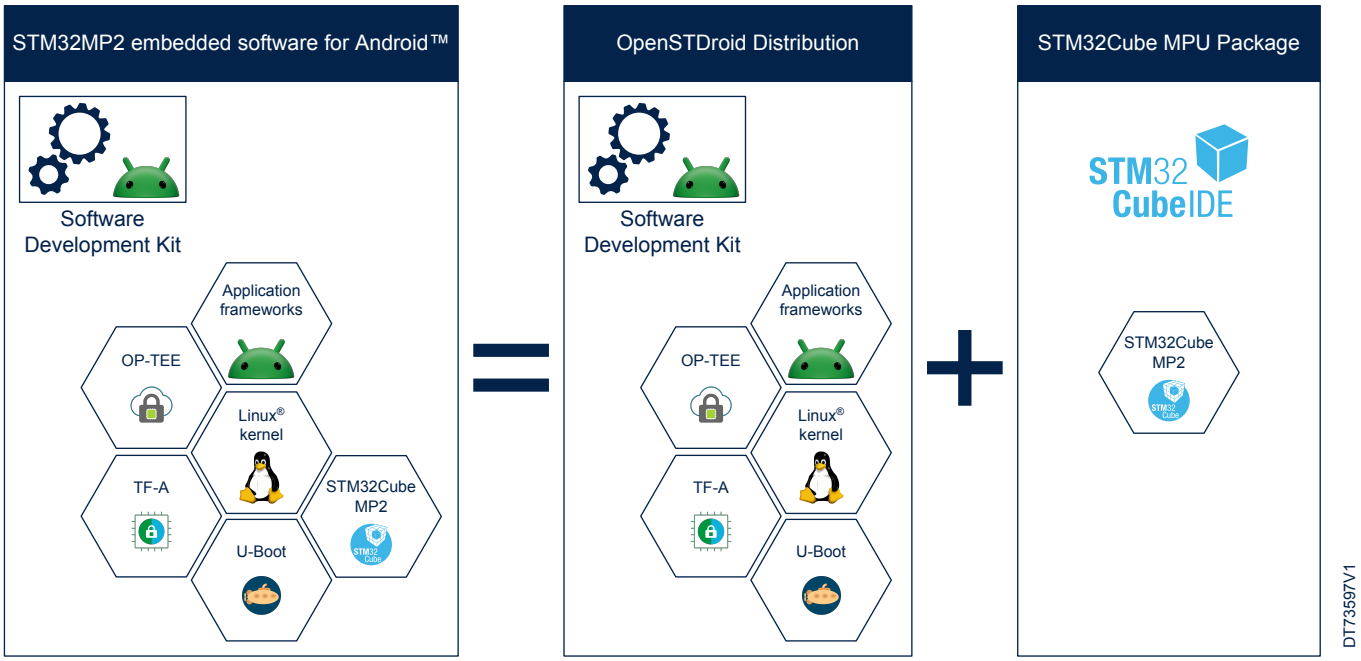
The STM32MP2DroidDis OpenSTDroid Distribution Package is based on the Android™ build framework. It runs on STM32MP2 microprocessors featuring Arm® Cortex® processors.

Note: Android is a trademark of Google LLC.

Arm is a registered trademark of Arm Limited (or its subsidiaries) in the US and/or elsewhere.

Figure 1 shows how the STM32MP2 embedded software for Android™ is composed of the STM32MP2DroidDis OpenSTDroid Distribution Package and the STM32CubeMP2 STM32Cube MPU Package.

Figure 1. STM32MP2 embedded software for Android™



1.1 Ordering information

STM32MP2DroidDis is available for free download from the *www.st.com* website.

1.2 Versioning

The major and minor versions of the STM32MP2DroidDis OpenSTDroid Distribution Package are aligned on the major and minor versions of the OpenSTLinux Distribution. This prevents painful backward compatibility attempts and makes dependencies straightforward.

The STM32MP2DroidDis generic versioning vx.y.z is built as follows:

- **x**: major version matching the OpenSTLinux Distribution major version. Each new major version is incompatible with previous OpenSTLinux Distribution versions.
- **y**: minor version matching the OpenSTLinux Distribution minor version. Each new minor version might be incompatible with previous OpenSTLinux Distribution versions.
- **z**: patch version to introduce bug fixes. A patch version is implemented in a backward-compatible manner.

1.3 License

STM32MP2DroidDis is delivered under the *Mix Ultimate Liberty+OSS+3rd-party V1* software license agreement (SLA0048).

Software component license agreements

The software components provided in this package come with different license schemes. Refer to wiki.st.com/stm32mpu/wiki/STM32MP2DroidDis_licenses for details.

Revision history

Table 1. **Document revision history**

Date	Revision	Changes
08-Nov-2024	1	Initial release.

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